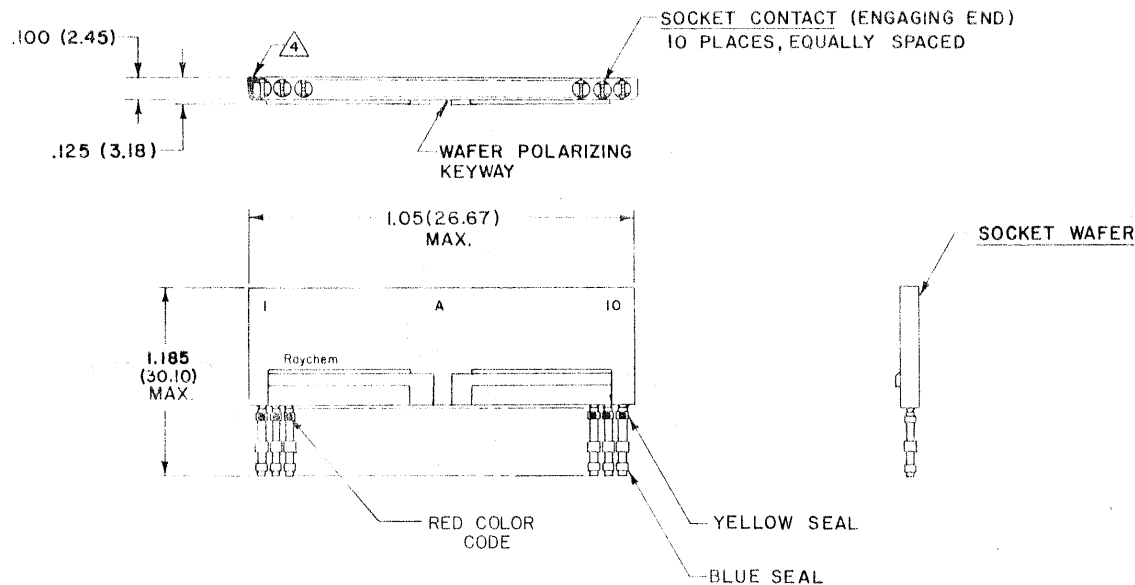
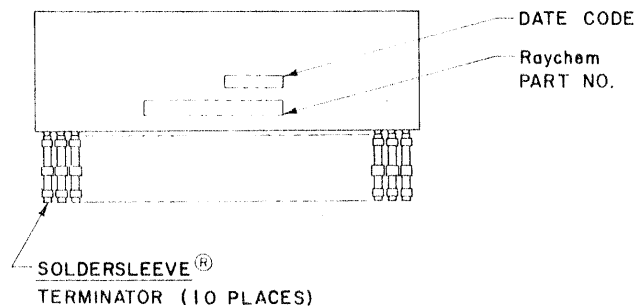




REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
2	REVISED PER ECN # T-5869	4/1/83	J.S.
1	RELEASED FOR PRODUCTION PER ECN T-012433	3/15/83	J.S.



5 WEIGHT (MAX.): LBS. GRAMS
.0054 2.46

4 SOCKET NUMBER ONE IS MARKED IN CONTRASTING COLOR.

3. FINISH: 3-A SOCKET WAFER; FINISH TO BE AS MOLDED.
3-B SOCKET CONTACT; GOLD PLATE PER MIL-G-45204 CLASS I.
(ENGAGING END)
3-C CONTACT TAIL; COATED WITH Sn63 SOLDER PER QQ-S-571
2. MATERIAL: 2-A SOCKET WAFER; HIGH GRADE POLYARYLENE THERMOPLASTIC.
2-B SOCKET CONTACT; COPPER ALLOY PER QQ-B-750.
2-C SOLDERSLLEEVE® TERMINATOR; REFER TO RAYCHEM DWG. CTA-0068 FOR DATA.

1. THIS WAFER ASSEMBLY USED IN MTC100 CONNECTORS.

NOTES:

If this document is printed it becomes uncontrolled.
Check with the web for latest revision.

SPECIFICATION CONTROL DRAWING Raychem Corporation 1983

DRAWN	HAWKINGS	11-16-83	Raychem RAYCHEM CORPORATION 300 CONSTITUTION DRIVE MENLO PARK, CALIFORNIA 94025	
CHECKED	J.S.			
APPROVED	Blair	12-2-83	TITLE WAFER ASSEMBLY, SOCKET, "A" STYLE, 1", 10 CONTACTS, WITH OVAL ENTRY FOR 20-26 AWG. TEMP. RATING 125°C MTC100 SERIES	
APPROVED	Lawson	12-2-83		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES (0.05 METRIC DIMENSIONS ARE IN PARENTHESIS (MM))			SIZE	CODE IDENT NO.
DO NOT SCALE THIS DRAWING			C	06090
			DWG NO.	MTC100-JAI-S14
			WEIGHT	△
			SHEET	1 OF 1